MPU-3000 & MPU-3050 3-Axis Evaluation Board User Guide Revision 2.0

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1. Revision History

Date	Revision	Description
10/01/2010	1.0	Initial release
07/15/2011	2.0	Added compatibility for MPU-3050

2. Purpose

This document describes the hardware and circuitry on the MPU-3000™ & MPU-3050™ 3-Axis Evaluation (EV) Board. It covers applying the EV board to a larger system, understanding key signals and circuit functions, hardware jumper settings, and port connectors.

2.1 Usage

This evaluation board provides three axes of motion sensing, comprised of:

- X-, Y- and Z-Axis gyros with ±250°/sec, ±500°/sec, ±1000°/sec, ±2000°/sec selectable full-scale range.

- Digital data measured using on-chip ADCs, is transmitted over I²C or SPI interfaces.

The Evaluation board may be used by itself using SPI or I²C serial communications interfaces. Alternatively, it may be connected to InvenSense's ARM Evaluation Board (INVARMEVB) for connectivity to a host computer using USB interface.

2.2 Related Documents

The following documents are recommended for additional information regarding the products and systems described in this Application Note.

- MPU-3000 & MPU-3050 Product Specification

- MPU-3000 & MPU-3050 Register Map and Register Descriptions

- MPU-3000 & MPU-3050 EVB schematics

3. MPU-3000 & MPU-3050 3-Axis EV Board Overview

The MPU-3000 & MPU-3050 3-Axis EV Board contains the MPU-3000 or MPU-3050 Digital Motion Processing Unit. It contains a number of 'solder-across' jumper points that permit several circuit configurations.

Refer to Figure 1. The EV Board is populated on its top side only for easy of measurement access. The 10x2 customer header connector is designed to connect with the InvenSense ARM Evaluation Board (INVARMEVB), which is a host microcontroller board useful for adapting the MPU-3000 & MPU-3050 3-Axis EV Board to a personal computer via its USB port.
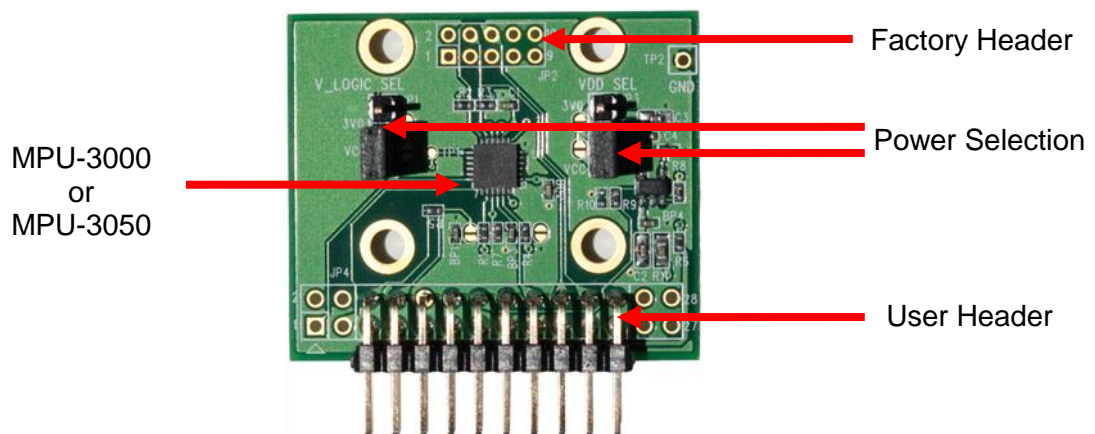

Figure 1. Top side of the MPU-3050 3-Axis EV Board

The 5x2 extension factory header is intended for connecting additional devices to the EV Board, such as a camera image stabilization processor, or a digital-output compass, etc. The 3-pin power selection headers are used to select which voltage supply is fed to the MPU-3000 & MPU-3050.

3.1 MPU-3000 & MPU-3050 Key Function and Pin-outs

The MPU-3000 & MPU-3050 EVB is a fully-tested evaluation board, providing for quick evaluation of the MPU-3000 & MPU-3050's X- , Y- , and Z-axis angular rate gyroscope. The MPU-3000 & MPU-3050 use InvenSense's proprietary MEMS technology with vertically driven vibrating masses to produce a functionally complete, low-cost motion sensor. All required conditioning electronics are integrated into a single chip measuring 4 x 4 x 0.9mm. It incorporates X- , Y- and Z-axis low-pass filters and an EEPROM for on-chip factory calibration of the sensor. Factory trimmed scale factors eliminate the need for external active components and end-user calibration. A built-in Proportional-To-Absolute-Temperature (PTAT) sensor provides temperature compensation information. The product is lead-free and Green Compliant.
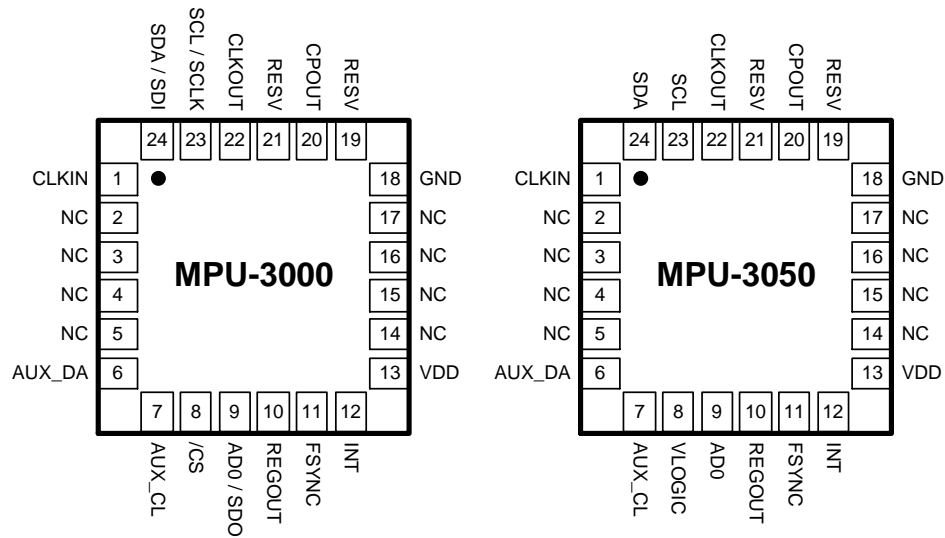

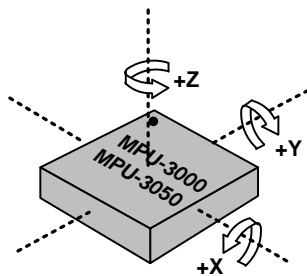**Figure 2. MPU-3000 & MPU-3050 QFN Package (Top View) 24-pin 4mm x 4mm x 0.9mm**

Figure 3. Orientation of Axes of Sensitivity and Polarity of Rotation

3.2 MPU-3000 & MPU-3050 Bus Connection

The MPU-3000 communicates to a system processor using either SPI or I^{2}C serial interfaces. The MPU-3050 communicates to a system processor using an I^{2}C serial interface. The device always acts as a slave when communicating to the system processor.
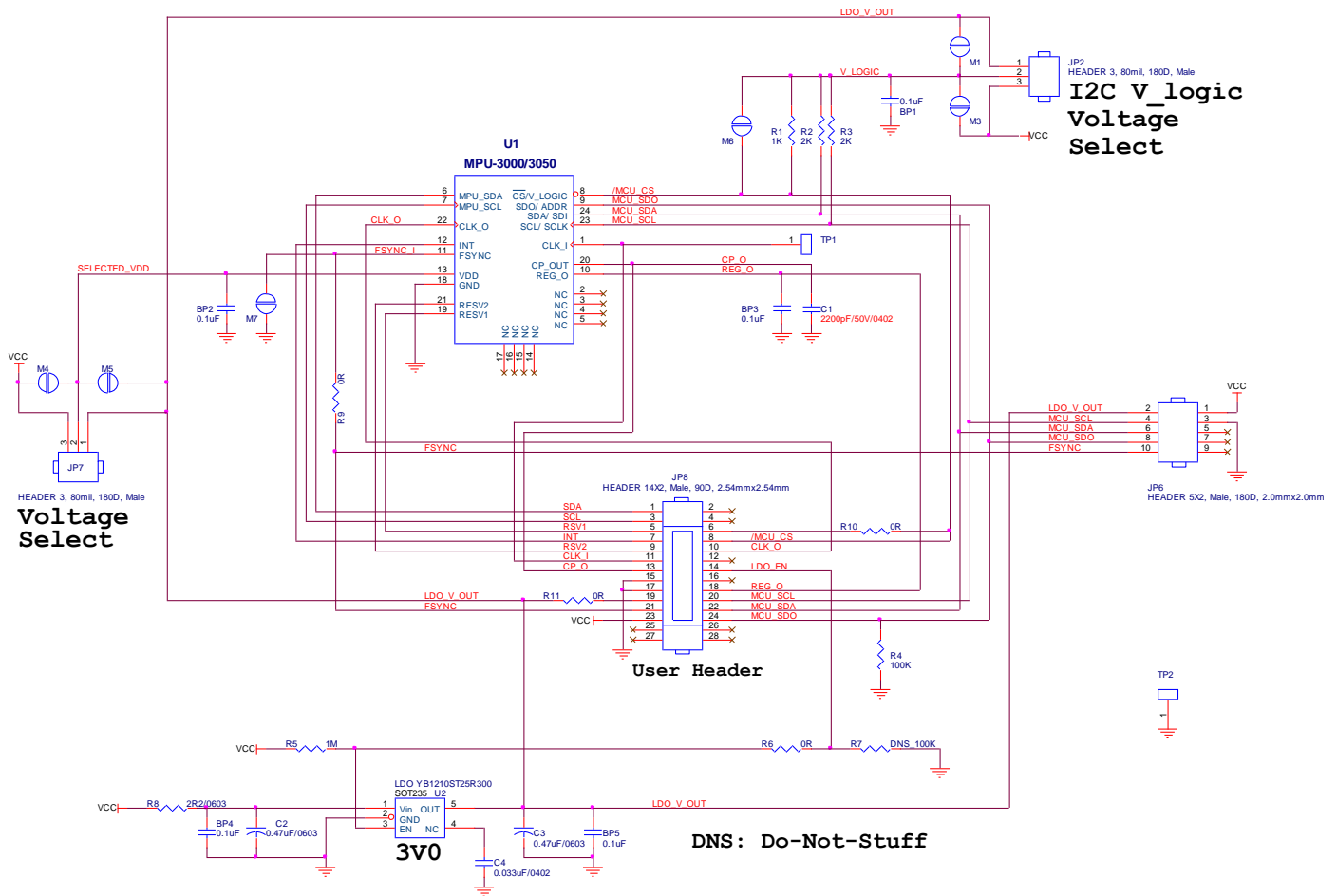
4. MPU-3000 & MPU-3050 3-Axis EVB Schematics

Figure 4. Schematics

4.1 Bill of Materials

Table 1. Bill of Materials

Item	Quantity	Reference	Part	PCB Footprint
1	5	BP1,BP2,BP3,BP4,BP5	0.1uF	C0402
2	1	C1	2200pF/50V	C0402
3	2	C2,C3	0.47uF/0603	C0603
4	1	C4	0.033uF	C0402
6	4	JP1,JP3,JP4,JP5	Solder	JP2P1_8X1_3S
7	2	JP2,JP7	HEADER 3, 80mil, 180D, Male	J79\3S
8	1	JP6	HEADER 5X2, Male, 180D, 2.0mmx2.0mm	SIP2X5N2
9	1	JP8	HEADER 14X2, Male, 90D, 2.54mmx2.54mm	HDB2X14NRA
11	2	R4,R1	100K	R0402
12	2	R3,R2	10K	R0402
13	1	R5	1M	R0402
14	1	R8	2R2/0603	R0603
17	1	U1	MPU-3000, 24-Lead QFN (4mm x 4mm x 0.9mm)	QFN5_5S24P0_5T
18	1	U2	YB1210ST25R300	SOT235

4.2 Power Supply Connections

JP2 and JP7 are 3 header-pin plug-in jumpers which allow users to select between on-board LDO and external DC supply to the MPU-3000 & MPU-3050. For details, please refer Table 2. Power Selection Jumpers.

The on-board 3.0V LDO (Low-dropout voltage regulator) is a low-noise version with stable enable-disable profile. Its output is called 3V0 on the schematic, and using it will assure that the gyroscope and accelerometer performance will meet intended specifications.

Selecting the raw Vcc line to power the chip is generally done while designing and evaluating an embedded platform, where the host processor and related electronics needs full control over the motion processing chipset's power supply.

When user intends to use on board LDO 3V0 power, external Vcc must be provided with higher than 3.7V to ensure that the LDO works properly.

If user provides Vcc with 5V, JP2 and JP7 must be set as "1-2 short". MPU-3000 & MPU-3050 VDD and VLOGIC operation range is 2.1V to 3.6V.

4.3 MPU-3000 & MPU-3050 EVB connector signals description

Table 2. Power Selection Jumpers

JP2 Pin Number	Signal description
1-2 short	VLOGIC = 3V
2-3 short	VLOGIC = Vcc (from external)
JP7 Pin Number	Signal description
1-2 short	VDD = 3V
2-3 short	VDD = Vcc (from external)

Table 3. User Interface Connector Signals

JP8 Pin Number	Signal description
1	Reserved
3	Reserved
5	Reserved
7	INT, INT output to controller
9	Reserved
11	CLK_I
13	CPOUT
15	GND
17	GND
19	3V
21	FSYNC
23	Receive power from ARM-7 Controller Board or external. It should be 5V, with >200mA
25	NC
27	NC
2	NC
4	NC
6	NC
8	SPI CS
10	Reserved
12	NC

Website: http//www.invensense.com

JP8 Pin Number	Signal description
14	EVB on board LDO enable
16	NC
18	REGOUT
20	I²C SCL or SPI SCLK
22	I²C SDA or SPI SDI
24	I²C Addr or SPI SDO
26	NC
28	NC

Table 4. Extended Factory Connector

JP6 Pin Number	Signal description
1	VCC, power from ARM-7 controller board or external power. It should be 5V, with >200mA
3	GND
5	NC
7	NC
9	NC
2	3V
4	I²C SCL or SPI SCLK
6	I²C SDA or SPI SDI
8	I²C Addr or SPI SDO
10	FSYNC

4.4   Connecting the FSYNC Line

The FSYNC line is intended for use in a camera's image-stabilization system. It is an input from the camera platform to the EV Board, and is intended to synchronize the MPU-3000 & MPU-3050's serial bus transfer with the master timing set by the camera system. FSYNC can originate from the host processor via JP8 pin-21, or from JP6 pin-10. There is no external pull-up termination for the FSYNC line.

4.5   Serial bus Levels, Speeds and Terminations

The MPU-3000 & MPU-3050 support I²C up to 400kHz, and SPI (MPU-3000 only) up to 1MHz serial clock rates. The I²C bus open drain pull up resisters are connected to either 3.0V or external provided Vcc (3V or 5V depend on user). The pull up level is selected by JP2. Please refer to Table 2. Power Selection Jumpers.

5.   Data Gathering Options

The MPU-3000 & MPU-3050's Digital Sensor Data is available at the User Header. Alternatively, for connectivity with a host PC, an InvenSense ARM Processor Board may be used.

5.1   Connection to ARM EVB

For communications via USB to a host computer, the MPU-3000 & MPU-3050 EVB can be connected to InvenSense's ARM processor board, the INV-ARMEVB.

The photo below shows the connection of MPU-3000 & MPU-3050 to INV-ARMEVB. Connection between the two boards is made via the user header.
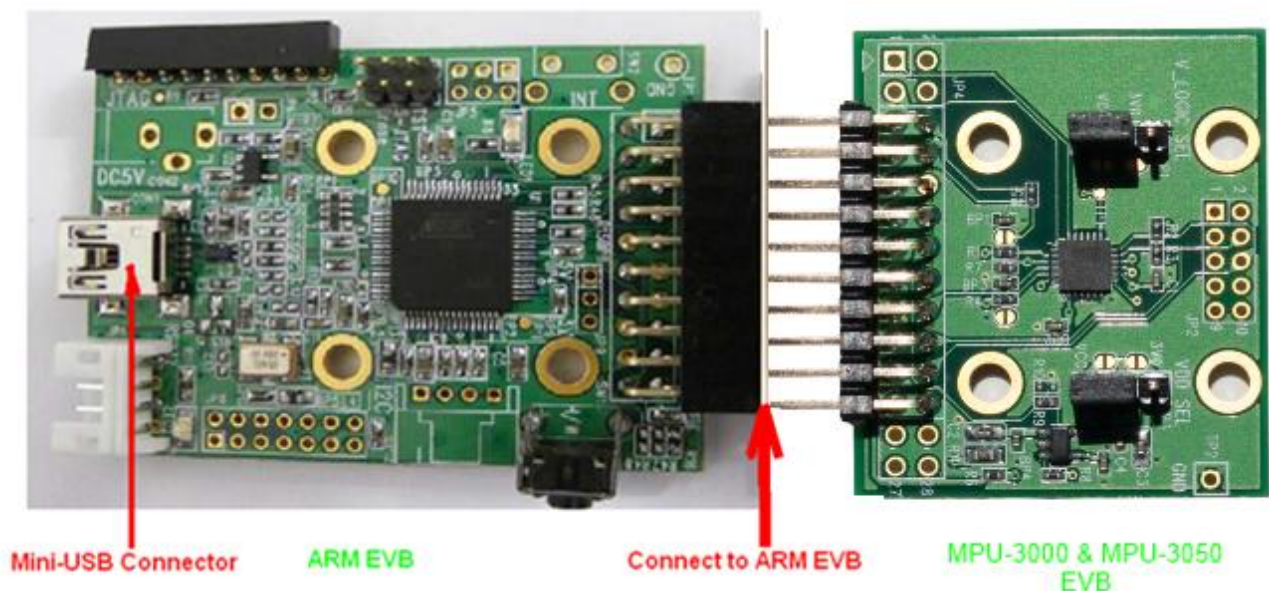

Figure 5. Connect MPU-3000 & MPU-3050 EVB to ARM Board

1.1 Use of MPU-3000 & MPU-3050 without ARM EVB board

I²C and SPI signals are available on JP8 and JP6. User can develop tools to communicate with the MPU-3000 & MPU-3050. There is no bus mode selection setting needed.

6. Special Instructions

6.1 Electrostatic Discharge Sensitivity

The MPU-3000 & MPU-3050 gyro can be permanently damaged by an electrostatic discharge. ESD precautions for handling and storage are recommended.

7. Dimension Drawing

The MPU-3000 & MPU-3050 EV board is a 4 layer PCB with 32mm x 38mm dimension.
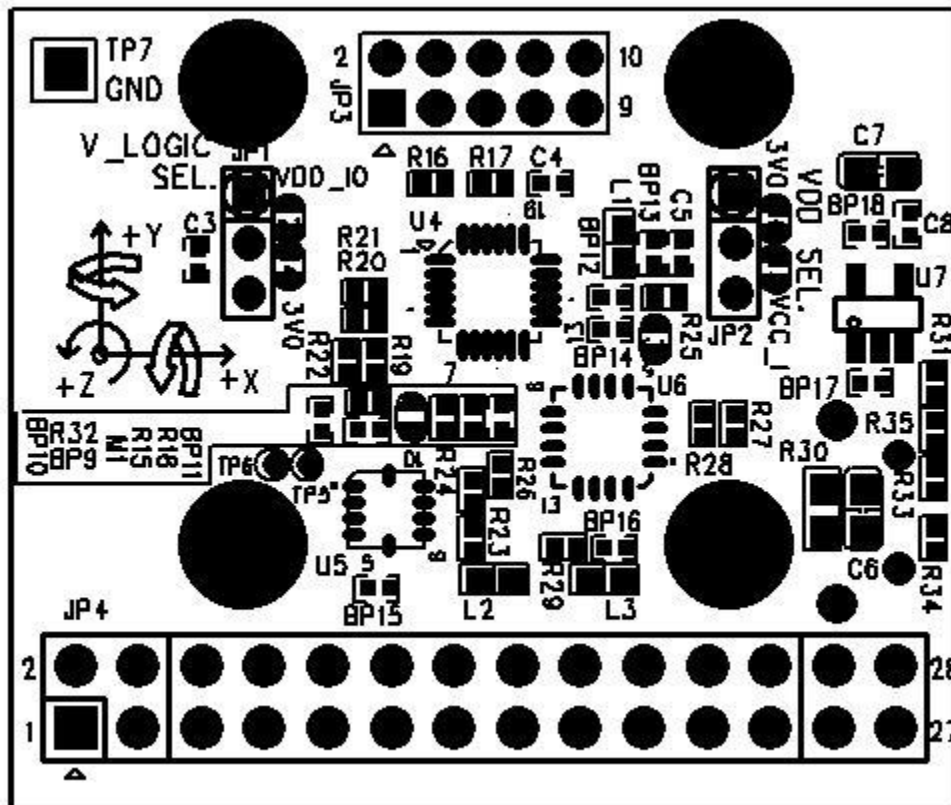

Figure 6. MPU-3000 & MPU-3050 EVB Dimensions

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